



# X2000DF series

LASER DIRECT IMAGING FOR PCB INNER- AND OUTER LAYER PATTERNING



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The LIMATA **X2000 Series** is a laser direct imaging system platform designed for the patterning of PCB inner and outer layers.

The X2000 platform is standardly equipped with a double drawer system including parallel registration. With this feature, the PCB patterning process can be reduced from four process steps (including loading, registration, imaging, unloading) down to only one step (imaging). A fully automated X2000 twin-set option provides further capacity for high-volume PCB production.

**Best in class registration** of the panel is guaranteed by using a multi-point sub-registration method without any loss in capacity and non-linear scaling. Up to 4 HD cameras with RGB light can detect the reference marks without influencing production throughput.

The **X2000** system combines different laser diode wavelengths in parallel working and precise laser spots. The use of cost-efficient high energy UV diode-lasers with lifetimes of over 25,000h support lower total costs of ownership.

Finest lines and spaces are achieved by using a **variable beam shaping optic (HD/HR-option)**, which provides for an automatic laser spot size alignment during the imaging of standard PCB and HDI applications.

Full PCB product traceability and data exchanges via MES & Secs/Gem interfaces can be provided.

Availability of complementary **automation options** for fully automated single or dual LDI-system operation

### **Features and Benefits**

- New flexible laser direct imaging platform for the production (patterning) of standard, advanced and custom PCB applications
- High volume production capability with an automated in-line LDI system set-up
- Double drawer system significantly improves cycle time and throughput (panels/h)
- Unique modular multi-wave laser set-up with +25.000 hours' lifetime.
  The optimum laser capacity set-up can be selected and configured according to customer needs
- Highest optical depth of focus (+/-500µm) guarantees constant resolution without limitation
- Optimized machine footprint for PCB manufacturing lines with space restrictions
- **Ease-of-use** operator friendly handling and data interface

# **Applications**

· Standard PCB and HDI production

Consumer electronics, automotive, industrial, military, aerospace, medical

· Custom PCB production

Thick copper

### **REM** examples







Mariliana ta Isiada cadana DCD a

### **System specifications**

Market:	Medium to high-volume PCB production		
Operating table:	Dual table		
Vacuum table:	Included		
Mechanical system:	XY linear drive gantry system		
Base:	Full granite		
Weight:	ca. 4.500 kg		
Dimensions:	1,5m x 3,2m x 1,95m / 59" x 126" x 76"		
Footprint:	4,8 m <sup>2</sup>		
Communication interface:	Ethernet		
Power supply:	400 VAC / 3+1 Phase		
Upgradeable:	Up to 4 heads		
Max. image size:	710 x 610 mm2 / 28" x 24"		
Max. panel thickness:	25μm - 15 mm / 1mil - 0.6"		

### **Imaging Features**

UV Light engine:	Diode lasers
UV Laser wavelength:	400-410 nm
UV & IR Lifetime laser [typ.:]	> 25.000 h
UV Lasers per head:	4 - 6
Number of heads (exposure units):	1 - 4 heads
Depth of focus:	+/- 500μm / 20mil

### Resolution Accuracy\*\*

Min. dams:	50 μm / 2 mil
Min. Space:	50 μm / 2 mil
Min. Lines (HD-Option):	25 μm / 1 mil
Min. Space (HD-Option):	25 μm / 1 mil
Max. edge roughness:	+/- 10% min. res.
Max line width tolerance:	+/- 10% min. res.

### **Registration Features**

Resolution Accuracy**	
Reg. System:	Up to 4 x HD Cameras
Camera Lighting:	RGB
Top to bottom layout [typ.]:	up to +/- 10 μm / 0.4 mil

For more information please contact us:

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<sup>\*</sup> depending on fiducial and layout quality

<sup>\*\*</sup> depending on resist materia

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### **System options**

### **HD-Option**

- Adjustable laser spot size for advanced HDI production
- Processing of lines / spaces down to 1 mil /25 um

### **Multi-Point Registration**

- Detection of multiple fiducials for max. registration quality
- No cycle time loss from registration due to parallel working HD camera systems and double drawer handling approach



 Automated tracking of individual QR- and Barcodes or serial numbers as well MES-interface programming options for full product traceability

### Pin-Less UV-marking System

 Detection of inner layers without any holes

### **Automation**

 The X2000 platform can be complemented by a robotic set-up for a fully automated and less labor intensive LDI in-line operation production demands

















### X2000DF modular system configurations



LDI System family	X2200-DF	X2300-DF	X2400-DF
UV laser heads	2	3	4
UV diode lasers per head	4/6	4/6	4/6
Total UV lasers	8/12	12/18	16/24

## **Modularity**



